

Component (Fig. 1)

Quad Flat Pack (QFP)

Pitch.....	0.80
Pins A.....	8
Pins B.....	8
Pin Count.....	32
L1min.....	8.80
L1max.....	9.20
L2min.....	8.80
L2max.....	9.20
Tmin.....	0.45
Tmax.....	0.75
Wmin.....	0.30
Wmax.....	0.45
Amin.....	6.80
Amax.....	7.20
Bmin.....	6.80
Bmax.....	7.20
Hmax.....	1.20
Kmin.....	0.05

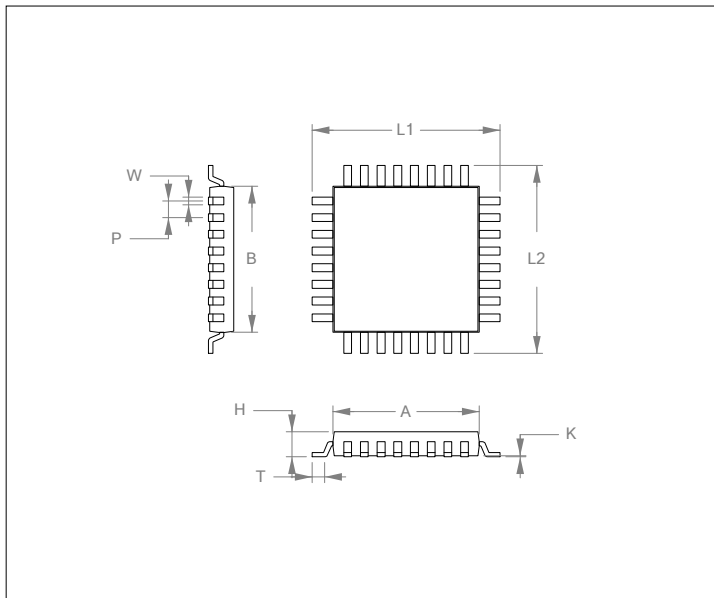


Fig.1

Solder Joint Goals (Fig. 2)

Environment is B - NOMINAL

Toe (Outside) Goal.....	0.35
Toe min.....	0.34
Toe max.....	0.55
Heel (Inside) Goal.....	0.35
Heel Min.....	0.30
Heel max.....	0.60
Side Goal.....	0.03
Side Min.....	0.02
Side max.....	0.13

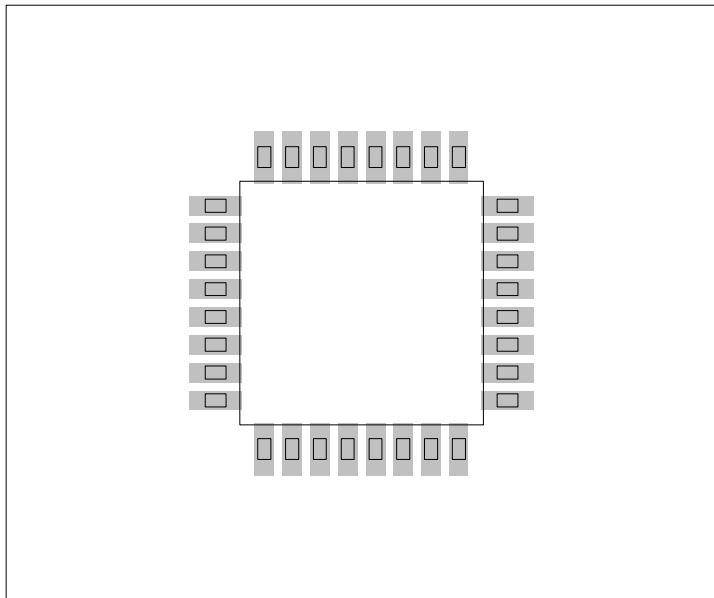


Fig.2

Land Pattern (Fig. 3)

C1.....	8.40
Y.....	1.50
X.....	0.55
C2.....	8.40
Pin(s) default	
r150_55	

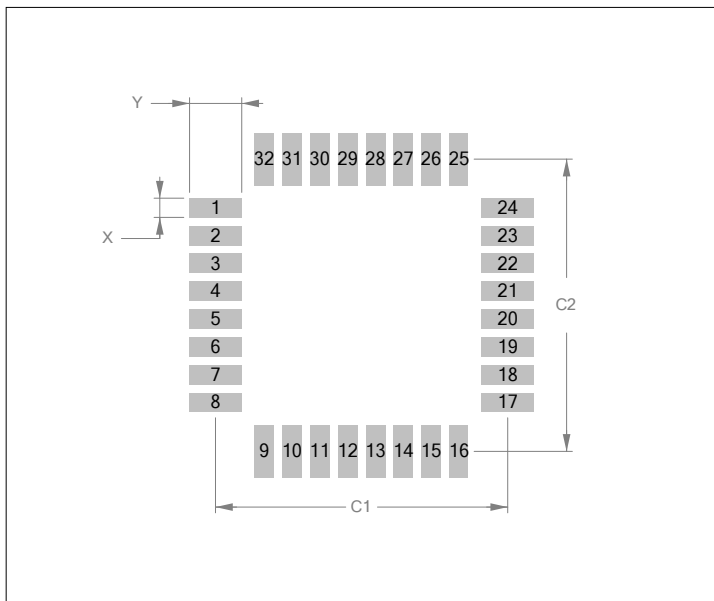


Fig.3

Silkscreen (Fig. 4)

R1.....6.20
 R2.....6.20

Assembly (Fig. 5)

Anom.....7.00
 Bnom.....7.00

Courtyard (Fig. 6)

V1.....10.40
 V2.....10.40

Program Version: 10.2.1

Advisories

No preference setting exists
 for component lead size

Land is being trimmed for
 lands that extend under the
 body.

Fig.4

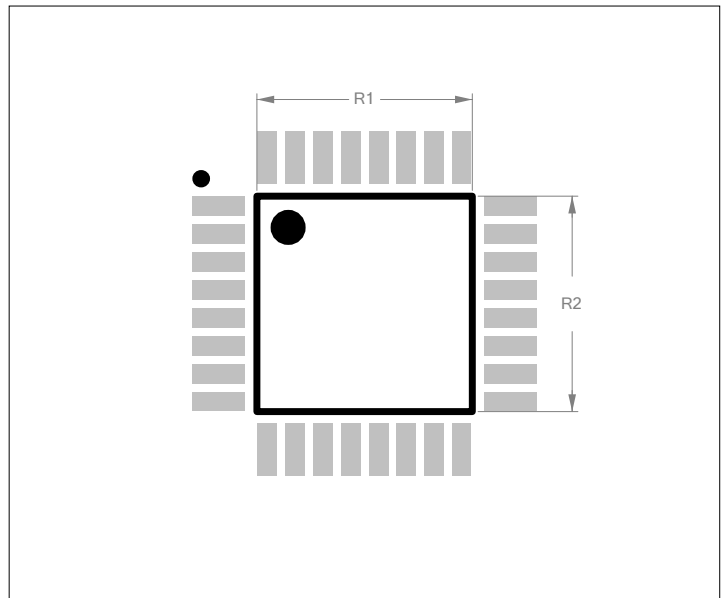


Fig.5

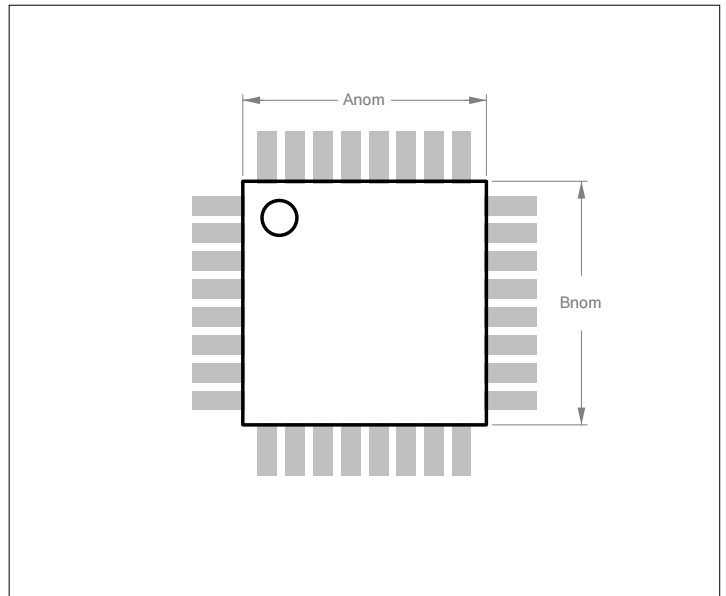


Fig.6

